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IEEE ELECTRONICS PACKAGING SOCIETY

CALL FOR PAPERS

The Leading International Components, Packaging, and Manufacturing Technology Symposium

10th IEEE CPMT Symposium Japan

November 10 – 12, 2021,

A Hybrid Event of On-site and Virtual Meetings

On-site Venue: Kyoto University Clock Tower Centennial Hall, Kyoto, JAPAN
https://www.ieee-csj.org/

"Electronics Packaging for 5G and B5G"

"IEEE CPMT Symposium Japan (ICSJ)" is one of the most widely recognized international conferences sponsored by the **IEEE Electronics Packaging Society (EPS)** and has been held annually in Kyoto in November. This conference was inaugurated in 1992 as "The VLSI Packaging Workshop in Japan (VPWJ)" to provide a platform for you to communicate and interact with global leaders in packaging technology. Later in 2010, this conference was renamed to "ICSJ" and ICSJ2021 is the 10th ICSJ meeting, or 19th conference since establishing VPWJ. This year, ICSJ2021 will be a hybrid event of on-site and virtual meetings where several presentation options are available for the authors to select and the details will be announced on the official website at a later date.

Electronics Packaging for 5G and B5G: The 5G commercial services have just began and provide higher transmission rate, lower latency, greater capacity of remote execution, and larger number of connected devices. The 5G advantages will dramatically advance the performance of IoT services, edge computing, augmented reality (AR) / virtual reality (VR), autonomous mobility, as well as artificial intelligence (AI), and future "beyond 5G (B5G)" mobile network will eventually provide 5G and B5G services to realize Internet of Everything (IoE) services. In 2021, our focus is on key electronics packaging technologies for the next-generation mobile networks and their applications for *5G and B5G* services, and emphasizes on the following main topics: **Photonics, Advanced Packaging, Process & Material, Power & Automotive Electronics, Bioelectronics,** and **Sensing Technologies**. Additional topics of primary interest to the participants are listed below.

Other topics include (but not limited to):

+ 3D Packaging & Chip-on-Chip
+ Advanced Fine Pitch Packaging, Micro Bumping & CSP
+ Board-Level Integration & Integrated Substrate
+ Laminated Materials & Processing, Materials for Packaging
+ Reliability & Failure Mechanisms
+ Packaging for High-Speed Electrical Interconnect
+ Signal Integrity & Power Integrity
+ RF Components & Modules
+ Additive Manufacturing & 3D Printed Electronics
+ Brain-like Neuromorphic Chip Assembly
+ Resilient Packaging for Autonomous System
+ Low Power, Low Temperature & Ultra Low Noise System Packaging

This conference is a perfect opportunity for you to communicate, interact, exchange technical ideas, and discuss your latest novel research findings in 5G and B5G packaging technologies with experts from industry and academia. In addition to the regular sessions, there is an "Early Career Researchers' (ECR)" session for young researchers with less than 2-year experience in their professions and all students including Ph.D. to hold fruitful communications with the experts. The ECR sessions have been held as a poster session in the past conferences.

Since ICSJ2021 is a hybrid virtual and on-site event, all ECR speakers of accepted abstracts must submit a professionally pre-recorded video of their poster presentation prior to the actual on-site face-to-face poster presentation. Authors are invited to submit an abstract through our website https://www.ieee-csj.org. **The abstract deadline is May 28, 2021**. Notification of acceptance will be sent by July 9, 2021, and the authors are requested to submit a 4-page manuscript by September 10, 2021 for the Technical Digest which will be available via **IEEE Xplore Digital Library**, whereas the authors for the ECR session are required to submit a 2-page manuscript.

Presentation options for the hybrid event:

ICSJ2021 will be a hybrid event for on-site meetings held in Kyoto University Clock Tower Centennial Hall, Kyoto, Japan and virtual meetings via online video conferencing, and the authors are requested to choose from the following options to give their presentation:

1) On-site oral presentation (remote discussion via interactive voice is available)

2) Virtual live and interactive oral presentation (remote discussion via interactive voice is available)

3) Virtual live and one-directional oral presentation (remote discussion via chat is available)

4) On-demand pre-recorded presentation (viewing only)

For plenary, special session, and invited speakers, the authors are requested to choose between option 1 and 2 to give their presentation. Whereas contributed speakers are requested to prioritize the options when submitting their proceeding paper and the mode of presentation will be assigned according to the capacity of the conference hall and speakers' preference.

Plenary, Special Session and Invited Speakers:

As of March 2021, the confirmed speakers are listed below:

Plenary Speakers:

Martin Shell	(Fraunhofer Heinrich Hertz Institute)
John H. Lau	(Unimicron Technology Corporation)
Roberto Sabella	(Ericsson)

Special Session Speakers:

Chris Bailey	(University of Greenwich)
Sam Karikalan	(Broadcom Incorporated)
Xiaoxiong Gu	(IBM T. J. Watson Research Center)
Robert Gee	(Continental Corporation)
Takehiro Nakamura	(NTT DoCoMo, Inc.)

Invited Speakers:

Ignazio Piacentini	(ficonTEC Service GmbH)	Chen-Chao Wang	(ASE, Inc.)
Agnes Tixier-Mita	(The University of Tokyo)	Ki-Hun Jeong	(KAIST)
Toru Ujihara	(Nagoya University)	Masahiro Horibe	(AIST)
Takashi Noma	(Murata Manufacturing Co., Ltd.)	Katsuya Kikuchi	(AIST)
Toshio Ito	(Shibaura Institute of Technology)	Dongshun Bai	(Brewer Science, Inc.)
Samuel Graham	(Georgia Institute of Technology)		

The above list of speakers will be updated and announced on the ICSJ official website.

ICSJ2021 Steering Committee:

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On-site Conference Venue:
Kyoto University Clock Tower Centennial Hall
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